



Principal Engineer, BE OSAT Package Develop Engineer Location Kanagawa

Job description

BE OSAT

Infineon outsource assembly (OSAT) Package Design and Development function (PAD)

Responsible for package design tasks in OSAT segment.
Manage package development execution within product and technology according to project requirement

- 1.Responsible for package development tasks as PAD function in OSAT : package definition, technology integration and project management for ATV and CCS business groups.
- 2.Own package design stage development milestone. Accountable to the project PJM.
- 3.Align on chip / package development, test concept for all technical, cost and quality during definition.
- 4.Define and select package solution according to product requirement (package type and BOM)
- 5.Tool up PRP, QTP, DFMEA. Project schedule, and alignment

Profile

- Native Japanese Speaker with excellent communication skill
- Business English skill(Email/Reading Manual/Conversation/Phone conversation /Teleconference) TOEIC700)
- Over 10 years experience for Automotive Semiconductor Package Development Package10
- Assembly
- PC SkillExcel, PowerPoint, etc.)
- Team Working /
- Bachelor Degree or Master Degree in Electronic Engineering or similar/

Why Us

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At a glance

Location:	Kawasaki (Kanagawa Science Park) (Japan)
Job ID:	349131
Start date:	as soon as possible
Entry level:	5+ years
Type:	Full time
Contract:	Permanent

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